

Refile
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22. A method of making a dielectric layer between a pair of opposing electrodes comprising the steps of:

forming, as said dielectric layer, an epitaxial thin film on a textured substrate;
forming one of said electrodes on an exposed surface of said thin film;
wholly or partially removing said textured substrate; and
forming an electrical connection to access said dielectric layer on the side of said textured substrate.

23.

The method according to Claim 22 wherein the textured substrate comprises nickel.

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The method according to Claim 22 wherein said epitaxial thin film is formed from perovskite.

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